MATERIAL DECLARATION SHEET

Package Type	TBU-Cxxx			
Product Line	Semiconductor Products			
Compliance Date	January 1, 2008			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (Subpart)	Homogeneous Material	Material Weight [g]	Homogeneous Material\ Substances	CAS Number if applicable	Materials Mass %	Material Mass % of Total Unit Weight	Subpart Mass of Total Wt. (%)
1	Encapsulation	Epoxy resin	0.03702	Epoxy Resin	Trade Secret	6	1.991	33.187
				Phenol Resin	Trade Secret	3	0.9956	
				Silica fused	60676-86-0	90.45	30.0176	
				Carbon Black	1333-86-4	0.55	0.1825	
2	Leadframe	Copper alloy	0.04728	Copper	7440-50-8	96	40.6896	42.385
				Iron	7439-89-6	2.2	0.9325	
				Zinc	7440-66-6	0.1	0.0424	
				Phosphorous	7723-14-0	0.075	0.0318	
				Lead (impurity)	7439-92-1	0.001	0.0004	
				Silver (Plating)	7440-22-4	1.624	0.6883	
3	Chip	Silicon	0.00668	Silicon	7440-21-3	100	5.988	5.988
4	Die Attach	Conductive Silver Epoxy	0.0174	Silver	7440-22-4	93.4	14.5685	15.598
				Epoxy resin	Trade Secret	5.5	0.8579	
				Polymeric compound	Trade Secret	0.55	0.0858	
				Functionalized Ester	Trade Secret	0.55	0.0858	
5	Bond wires	Gold	0.00023	Gold	7440-57-5	99.99	0.2059	0.206
				Potential impurities may include Ag, Be or Ca ≤ 30 ppm	7440-22-4; 7440-41-7; 7440-70-2	0.01	0.0001	

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6	Terminal Finish	Alloy	0.00294	Tin	7440-31-5	100.00	2.636	2.636
		Total Weight	0.11155					

Updated January 29, 2019

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